

Title (en)

NOVEL ADDITIVE COMPRISING LEAD AND/OR A LEAD ALLOY INTENDED TO TREAT BATHS OF LIQUID STEEL

Title (de)

NEUARTIGER ZUSATZSTOFF MIT BLEI UND/ODER EINER BLEILEGIERUNG ZUR BEARBEITUNG VON FLÜSSIGSTAHLBÄDERN

Title (fr)

NOUVEL ADDITIF COMPRENANT DU PLOMB ET/OU UN ALLIAGE DE PLOMB DESTINE A TRAITER LES BAINS D'ACIER LIQUIDE

Publication

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Application

**EP 08805930 A 20080604**

Priority

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- FR 0755486 A 20070605

Abstract (en)

[origin: WO2008152328A1] The present invention relates to an additive in the form of flux-cored wire intended for treating baths of liquid steel with a view to obtaining steels having a high lead content. The additive comprising metallic lead and/or one or more lead alloys according to the invention is intended to treat baths of liquid steel, and is in the form of flex-cored wire composed of a metal sheath and a finely divided filling material, the latter being composed of a powder of metallic lead and/or of lead alloy and of a powder containing a material capable of releasing a gas, which is inert with respect to the liquid steel, at the temperature of the liquid steel bath. Characteristically, said powder of metallic lead and/or of lead alloy consists of a particle size fraction GR between 200 µm and 500 µm and in that said particle size fraction GR has the following characteristics: - through a 200 µm sieve: GR < 5%; - through a 300 µm sieve: 90% ~ GR ~ 10%; - through a 400 µm sieve: 40%£ GR < 100%; - through a 500 µm sieve: 100% ~ GR ~ 90%.

IPC 8 full level

**C21C 7/00** (2006.01)

CPC (source: EP US)

**C21C 7/0056** (2013.01 - EP US); **C22C 33/00** (2013.01 - EP US)

Citation (search report)

See references of WO 2008152328A1

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